

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property
Organization
International Bureau



(43) International Publication Date
27 January 2005 (27.01.2005)

PCT

(10) International Publication Number
WO 2005/008767 A2

(51) International Patent Classification⁷: **H01L 21/60**,
23/485

(21) International Application Number:
PCT/IB2004/051175

(22) International Filing Date: 8 July 2004 (08.07.2004)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
03102190.0 16 July 2003 (16.07.2003) EP

(71) Applicant (for all designated States except US): **KONIN-
KLIJKE PHILIPS ELECTRONICS N.V.** [NL/NL];
Groenewoudseweg 1, NL-5621 BA Eindhoven (NL).

(72) Inventor; and

(75) Inventor/Applicant (for US only): **SOLO DE ZAL-
DIVAR, Jose** [ES/DE]; c/o Philips Intellectual Property
& Standards GmbH, Weissshausstrasse 2, 52066 Aachen
(DE).

(74) Agent: **MEYER, Michael**; Philips Intellectual Property &
Standards GmbH, Weissshausstr. 2, 52066 Aachen (DE).

(81) Designated States (unless otherwise indicated, for every
kind of national protection available): AE, AG, AL, AM,
AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN,
CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI,
GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE,
KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD,
MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG,
PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM,
TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM,
ZW.

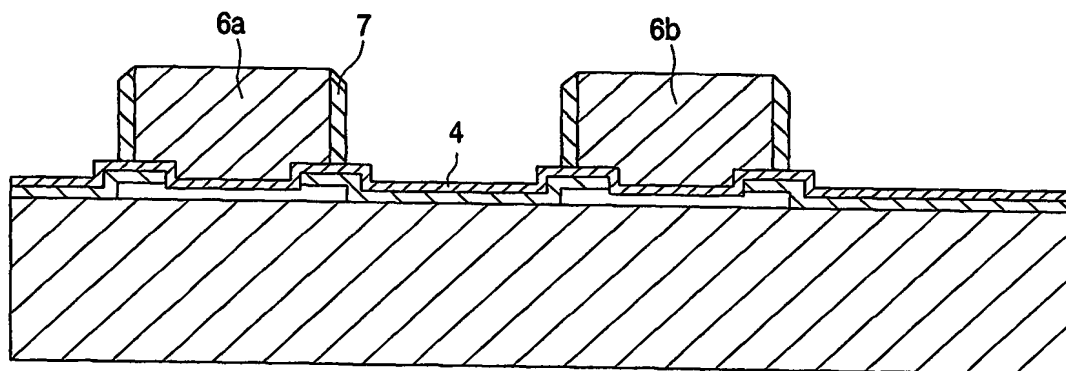
(84) Designated States (unless otherwise indicated, for every
kind of regional protection available): ARIPO (BW, GH,
GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM,
ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM),
European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI,
FR, GB, GR, HU, IE, IT, LU, MC, NL, PL, PT, RO, SE, SI,
SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ,
GW, ML, MR, NE, SN, TD, TG).

Published:

— without international search report and to be republished
upon receipt of that report

For two-letter codes and other abbreviations, refer to the "Guid-
ance Notes on Codes and Abbreviations" appearing at the begin-
ning of each regular issue of the PCT Gazette.

(54) Title: METAL BUMP WITH AN INSULATION FOR THE SIDE WALLS AND METHOD OF FABRICATING A CHIP
WITH SUCH A METAL BUMP



(57) Abstract: A chip with at least two metal bumps (6a, 6b) which has insulation layers for opposing side walls which are deposited in a plasma activated gas. Predetermined portions of the insulation layer (7) are removed by reactive ion etching. The metal bumps can be formed of a noble metal and the insulation layer of a dielectric material such as SiO₂ Si₃N₄.

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